

112G PORTFOLIO SOLUTIONS

TE Connectivity's (TE) 112G wide-ranging product portfolio provides a robust and flexible array of solutions to enable next generation architectures. The product family supports standard form-factors and performance requirements, designed with reliability and upgradability in mind, enabling applications including compute/storage, high-speed networking and machine learning/artificial intelligence.

Key Benefits

- Due to the demands on next generation high-speed designs, TE Connectivity (TE) has developed one of the most comprehensive, flexible and high-performing internal and external connector and cable assembly portfolios in the market
- Next generation products aligned with or exceeding the industry's 112G channel performance needs, delivering high marks in cross talk, return loss, and insertion loss performance
- Standard external input/output (I/O) form factors enable ecosystem connectivity for intra-rack and inter-rack applications
- Copper cable solutions provide cost-effective system design and connectivity options to achieve the performance demands of 112G architectures

Products

- **112G Product Support for SFP, QSFP, QSFP-DD and OSFP Interconnects**
 - Active Copper Cables (ACC)
 - Direct Attached Copper Cables (DAC)
 - I/O Connectors and Cages
- **STRADA Whisper Connectors, Cages, and Cable Assemblies / STRADA Whisper Absolute Connectors**
- **Over the Board (OTB) I/O Solutions**
- **Enabling 112G Through PCIe**
 - CEM Connectors
 - Sliver Product Family (SFF-TA-1002/SFF-TA-1020)
 - MCIO Product Family (SFF-TA-1016)
- **MULTI-BEAM and Busbar Power Connectors and Assemblies**



112G Portfolio Solutions



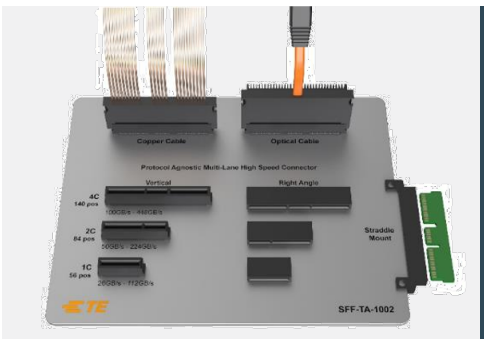
112G Per Lane I/O Solutions

- TE is on the leading edge of developing 112G per lane solutions for 800G and lower aggregate port bandwidths. Our designs are MSA specification compliant and deliver high performance
- Thermal management is becoming challenging across high speed IO connectors. TE has a wide portfolio of cage designs and mounts to fit various forced air and liquid cooling architectures dissipating 25W+ powers
- Offerings: OSFP, QSFP-DD, QSFP, SFP, SFP-DD, CDFP compliant products



Cabled STRADA Whisper Backplane Connectors

- Flexible solution to run longer channels
- Support 112G PAM4 and 56G NRZ
- Excellent EMI performance
- Cable receptacle also available



Sliver Interconnects for SFF-TA-1002

- The Sliver connector design was adopted as the standard connector design in the SFF-TA-1002 specification which was adopted in reference applications by OCP, EDSFF and Gen-Z
- Chosen for performance, density, flexibility and robustness
- Offerings: mid-board connectors, card edge connectors and cable assemblies



Sliver Internal Cabled Interconnects

- Slim interface supports wide variety of protocols
- Rated up to 112G PAM4 and 56G NRZ
- Sliver products comply with SFF-TA-1002 specification

112G Portfolio Solutions



Mini-SAS HD Connectors and Cable Assemblies

- Industry-proven solution to address SFF-8-86, 887, and 8088 standards
- Supports SAS 2.0, SAS 2.1, SAS 3 and PCIe applications
- Supports PCIe4 16G applications



Busbar Power Connectors

- Solutions for power delivery in server, switch, wireless, industrial control and modular power supplies. Commonly used in rack-mounted equipment with busbar architecture
- Benefits: Reliable, Low resistance, Robust
- Applications: IT Tray, Cubby Shelf, Battery Backup Unit (BBU) and Power Shelf



Busbar Power Assemblies

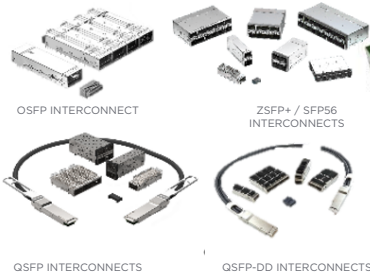
- Solutions for 12V and 48V requirements
- Benefits: reliable and robust power delivery
- Offerings: flexible, rigid, and laminated busbars
- End to end solution for power distribution and PCB interconnection

Product Interconnectivity

INTERNAL CARD EDGE CABLES & CONNECTORS



HIGH SPEED I/O INTERCONNECTS



POWER CONNECTORS & CABLE ASSEMBLIES



HIGH SPEED BACKPLANE CONNECTORS



HYBRID CABLE ASSEMBLIES



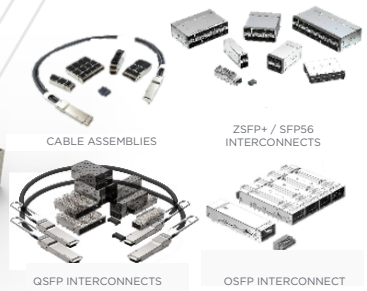
POWER CONNECTORS & CABLE ASSEMBLIES



HYBRID CABLE ASSEMBLIES



HIGH SPEED I/O INTERCONNECTS



INTERNAL CARD EDGE CABLES & CONNECTORS



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04/22 Original

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